

# SMB1N-880

- Infrared High Power LED
- 880 nm, 320 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 1.0 mm
- Viewing Angle: 128°

### Description





v 1.0 30.09.2014

SMB1N-880 is a surface mount AIGaAs High Power LED with a typical peak wavelength of 880 nm and radiation of 320 mW. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

### Maximum Ratings (T<sub>CASE</sub>=25°C)

Parameter	Symbol	Va	Unit		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		2000	mW	
Forward Current	IF		1000	mA	
Pulse Forward Current *1	IFP		3000	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	R <sub>THJA</sub>		10	K/W	
Junction Temperature	$T_J$		120	°C	
Operating Temperature	T <sub>CASE</sub>	- 40	+ 100	°C	
Storage Temperature	T <sub>STG</sub>	- 40	+ 100	°C	
Lead Solder Temperature *2	T <sub>SLD</sub>		+ 250	°C	

 $^{*1}$  duty=1%, pulse width = 10  $\mu s$   $^{*2}$  must be completed within 5 seconds

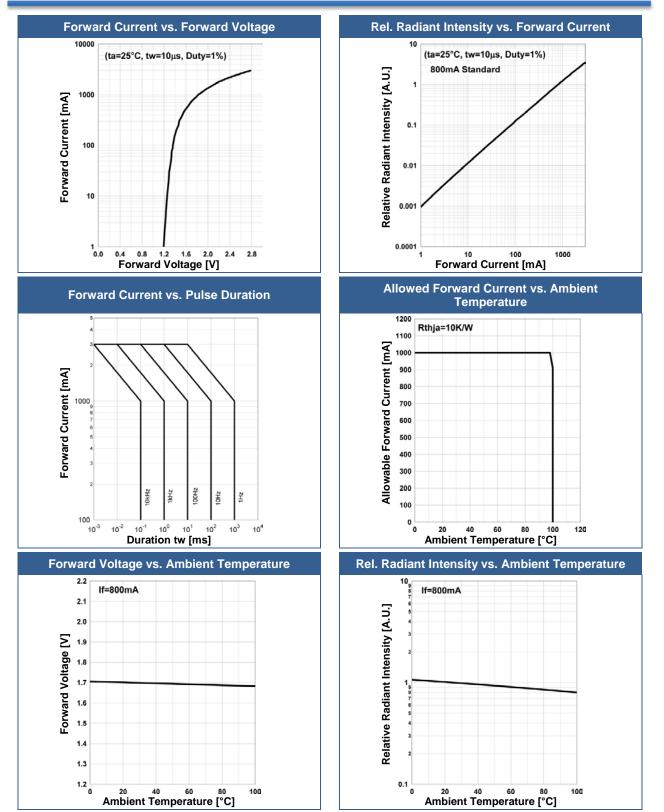
## Electro-Optical Characteristics (T<sub>CASE</sub>=25°C)

Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	$\lambda_P$	I <sub>F</sub> =800mA	870	880	890	nm
Half Width	$\Delta \lambda$	I <sub>F</sub> =800mA		50		nm
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =800mA		1.7	2.2	V
	V <sub>FP</sub>	I <sub>FP</sub> =3A		2.8		
Radiated Power *1	Po	I <sub>F</sub> =800mA	240	320		mW
		I <sub>FP</sub> =3A		1100		
Radiant Intensity *2	IE	I <sub>F</sub> =800mA		100		mW/sr
		I <sub>FP</sub> =3A		360		
Viewing Angle	φ	I <sub>F</sub> =100mA		128		deg.
Rise Time	t <sub>R</sub>	I <sub>F</sub> =800mA		40		ns
Fall Time	t <sub>F</sub>	I <sub>F</sub> =800mA		40		ns

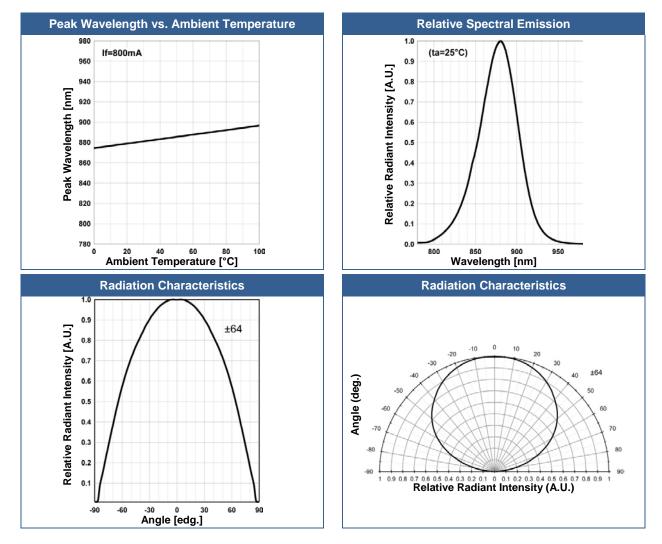
\*<sup>1</sup> measured by S3584-08
\*<sup>2</sup> measured by CIE127-2007 Condition B



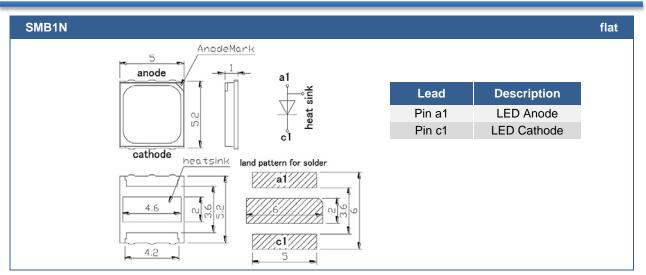
# Typical Performance Curves







### **Outline Dimensions**



All Dimensions in mm



### Precautions

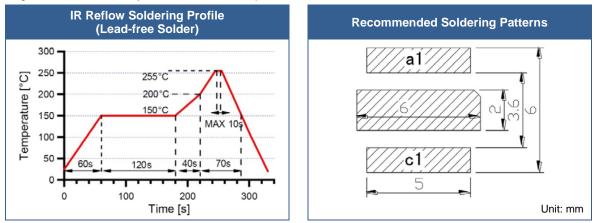
#### Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- · Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

#### **Recommended soldering conditions:**

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### **Cleaning:**

#### Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS DO NOT USE ultrasonic cleaners

#### Static Electricity:

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

#### **Operation:**

#### Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

© All Rights Reserved

The above specifications are for reference purpose only and subjected to change without prior notice